AAEON Technology INC
ISO-9001/14001 Certified
Industrial Automation PCs

GENE-6350 rev: A0.3 (AT Power)

Intel Low Voltage Celeron 650MHz

Temperature cycle Test Report

Report NO: 04E020033

Issued by:	Rex Chang	/	*08/18/2004*
	Test Engineer		**Date**
Reviewed by:	Wenyuan Yang	/	*08/18/2004*
	Manager		**Date**

Temperature cycle test

Report NO.04E020033

GENE-6350 A0.3 (AT Power)
Test Date: 08-13~17-2004

Test Product: GENE-6350 Rev: A0.3

Test Site: AAEON QA Internal Lab.

Performed By: Rex Chang

Test Standard: Reference IEC 68-2-61 Testing procedures
Test Z/ABD: Climatic Sequence Test
Reference IEC 68-2-30 Testing procedures
Test DB: Damp Heat Test

Test Equipment:
Programmable Temperature & Humidity Chamber
K.SON. INS. TECH. CORP.
Model: THS-D4H+-100
Date of Calibration: 05/24/04
Serial Number: 1241

Temperature & Humidity Cycle Test:

Testing Specification

Step	Temperature (℃)	Humidity (%RH)	Duration (HH:MM)
1	25	50	00:30
2	25	50	00:30
3	60	30	01:10
4	60	30	03:20
5	25	50	01:10
6	25	50	00:50
7	25	90	03:30
8	25	90	01:00
9	60	90	03:53
10	60	90	04:07
11	25	90	03:53
12	25	50	04:07
13	25	50	03:30
14	25	50	00:30
15	0	0	02:30
16	0	0	10:30
17	25	50	02:30
18	25	50	00:30

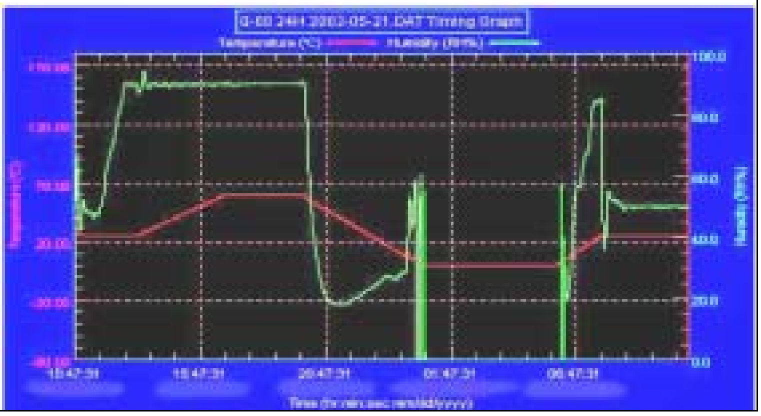
Test Curve:

Temperature & Humidity Power On/Off Test

Testing Specification:

Step	Temperature (℃)	Humidity (%RH)	Duration (HH:MM)
1	25	50	00:30
2	25	50	00:30
3	25	90	01:00
4	25	90	00:30
5	60	90	03:30
6	60	90	03:00
7	0	0	04:50
8	0	0	05:23
9	25	50	01:47
10	25	50	03:00

Test Curve:



Temperature cycle test

Report NO.04E020033

GENE-6350 A0.3 (AT Power)

Sample Configuration & Quantity Under Test:

1. CPU: Onboard Intel Low Voltage Celeron650MHz (Bios Ver.1.0)
2. SDRAM: 128MB TRANSCEND V58C2128804SAT75 SODIMM(DDR-266)
3. Chipset: VIA CLE 266 0334CE 2IA1014911
   / VIA VT8235CD 0331CD 23A30H7900
4. VGA: VIA CLE 266 integrated (Share memory up to 64MB) / 0334CE 2IA1014911
5. LAN: Realtek RTL 8100BL
6. CFD: SanDisk 32MB
7. Heat sink (P/N) :

Test Result :

Passed.

Test Method	Actual	Successful	Failure rate	Note
Power On/Off	2042	2038	0.2%	Pass

Note 1: There were 4 times booting fail during Power on/off test; two times at 60℃, and another at 0℃.
Note 2: The criterion of “ Power on/off test ” is the booting failure rate can’t over 0.2%